

10 9 8 7 6 5 4 3 2 1

F

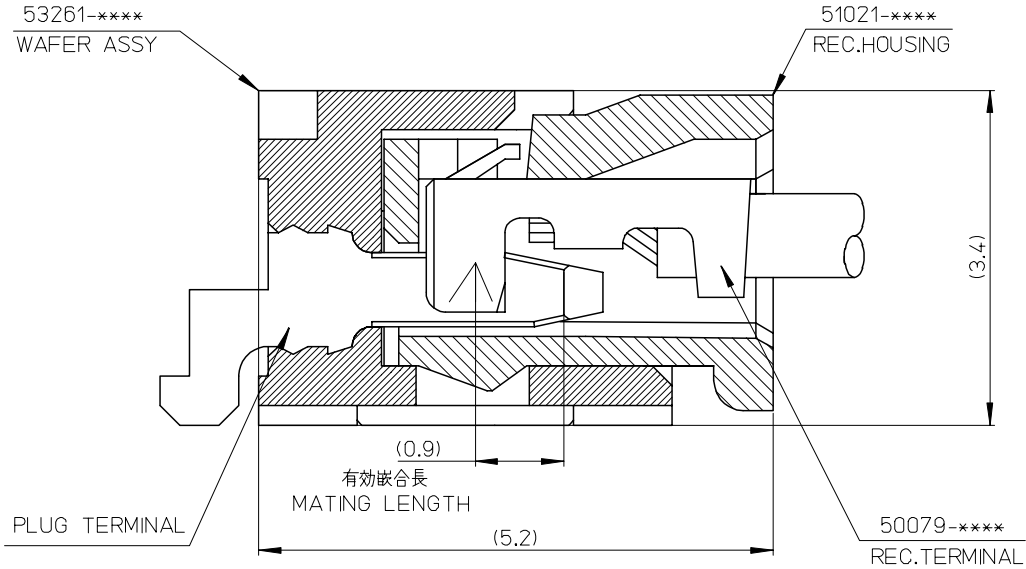
E

D

C

B

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1	
	ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9

8

7

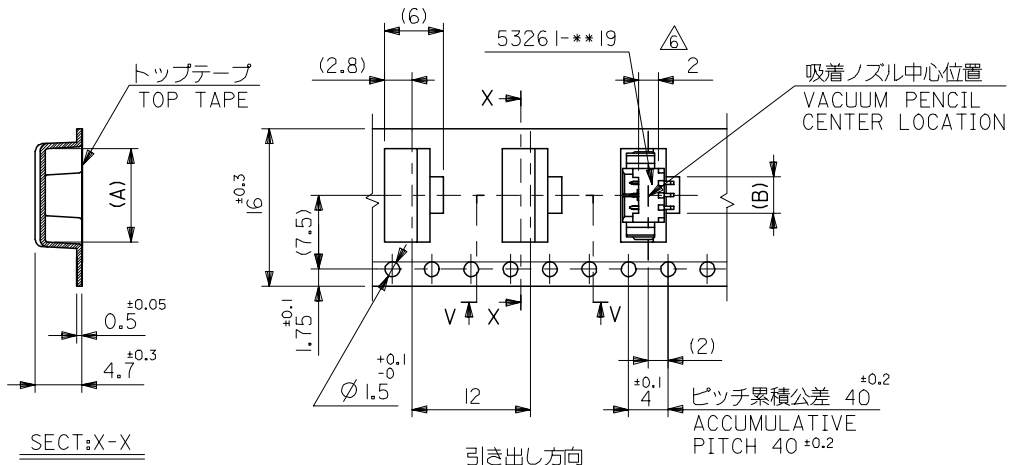
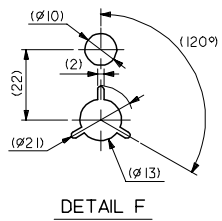
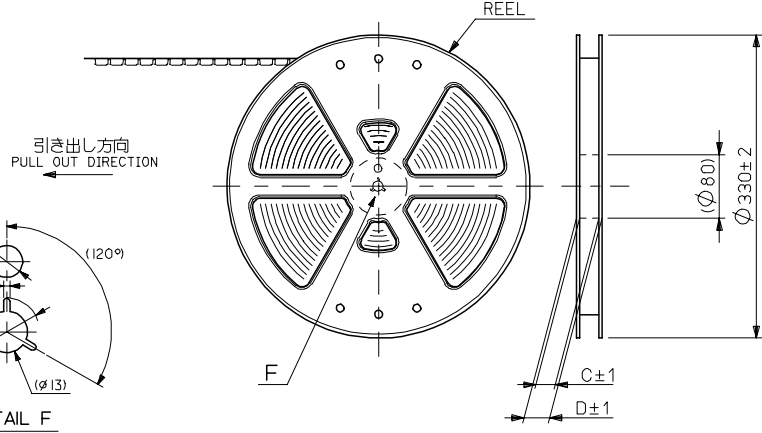
6

5

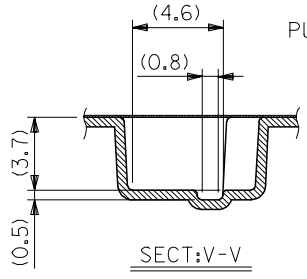
4

3

2



SECT:X-X



16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

注記  
NOTES

- 5326 I-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダ部 TOP TAPE LEADER PART 175 ±25  
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ±5
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

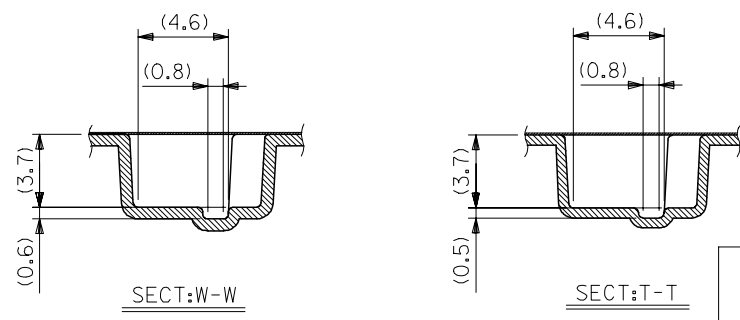
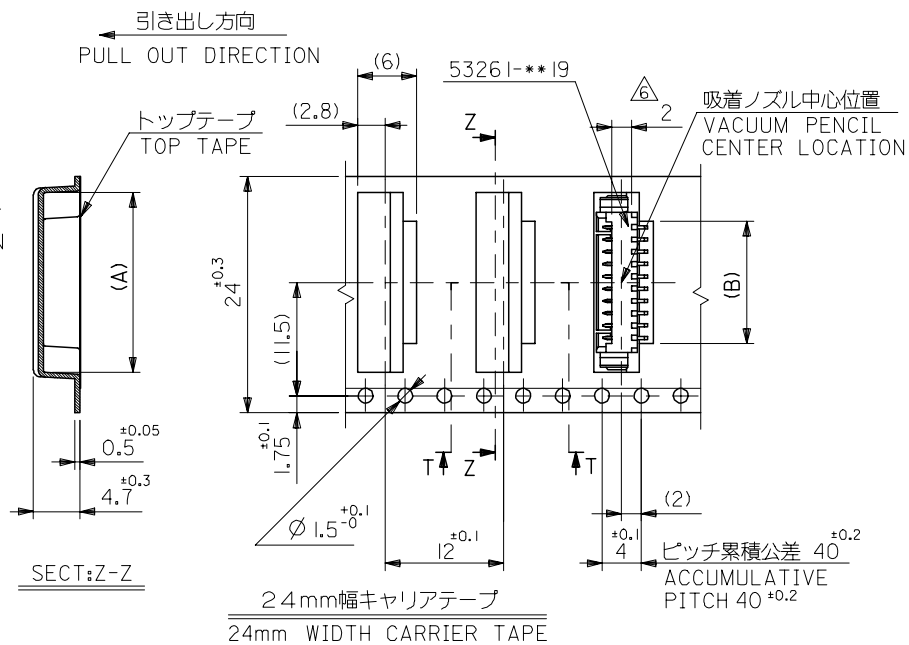
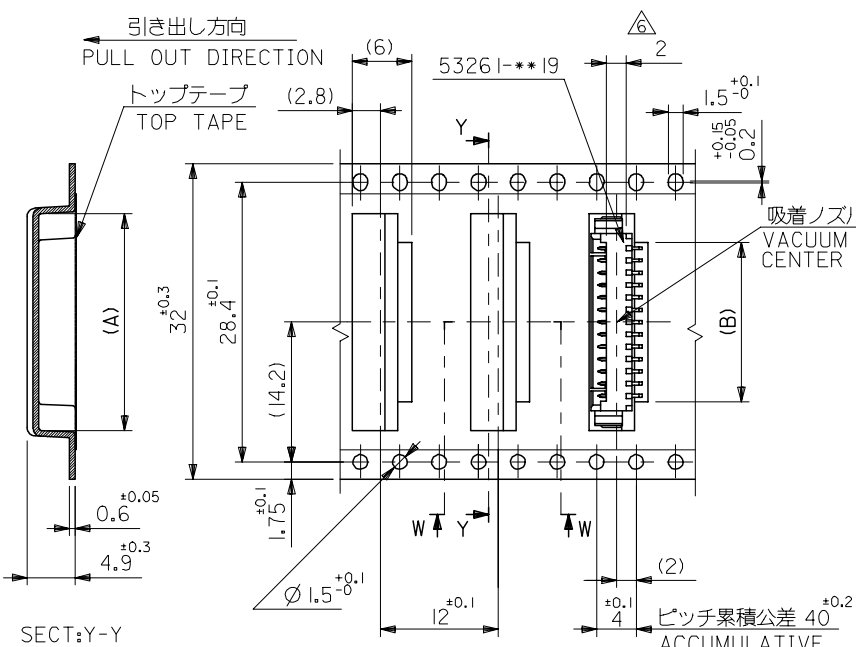
△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

6. 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90

7. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

16	21.4	17.4	3.7	9.5	5326 I-037 I	3
			2.45	8.25	5326 I-027 I	2
キャリアテープ幅 CARRIER TAPE WIDTH			D	C	B	A
MODEL NO.			SCALE		DESIGN UNITS	
53261-**-71			---		METRIC	
GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		THIRD ANGLE PROJECTION	
			MM ONLY		◎ □	

REVISED EC NO: J2008-0056 DRWNG: SALT001 CHKD: THARUYAMA APPR: NUKITA	DESCRIPTION 2007/07/31 2007/07/31 2007/08/10	10 UNDER ±0.2		DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
		10 OVER 30 UNDER ±0.25		CHECKED BY K. TOJO	DATE '04/02/06	
		30 OVER ±0.3		APPROVED BY M. SASAO	DATE '04/02/06	
		ANGULAR ±3 °		MATERIAL NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3



32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

MODEL NO. 53261-***71		キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	MATERIAL NO.	種数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE '04/02/06		MOLEX INCORPORATED			
30 OVER	±0.3	APPROVED BY M. SASAO		DATE '04/02/06					
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53261-023		2 OF 3			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

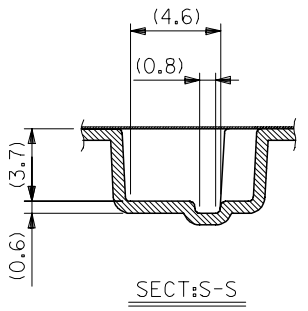
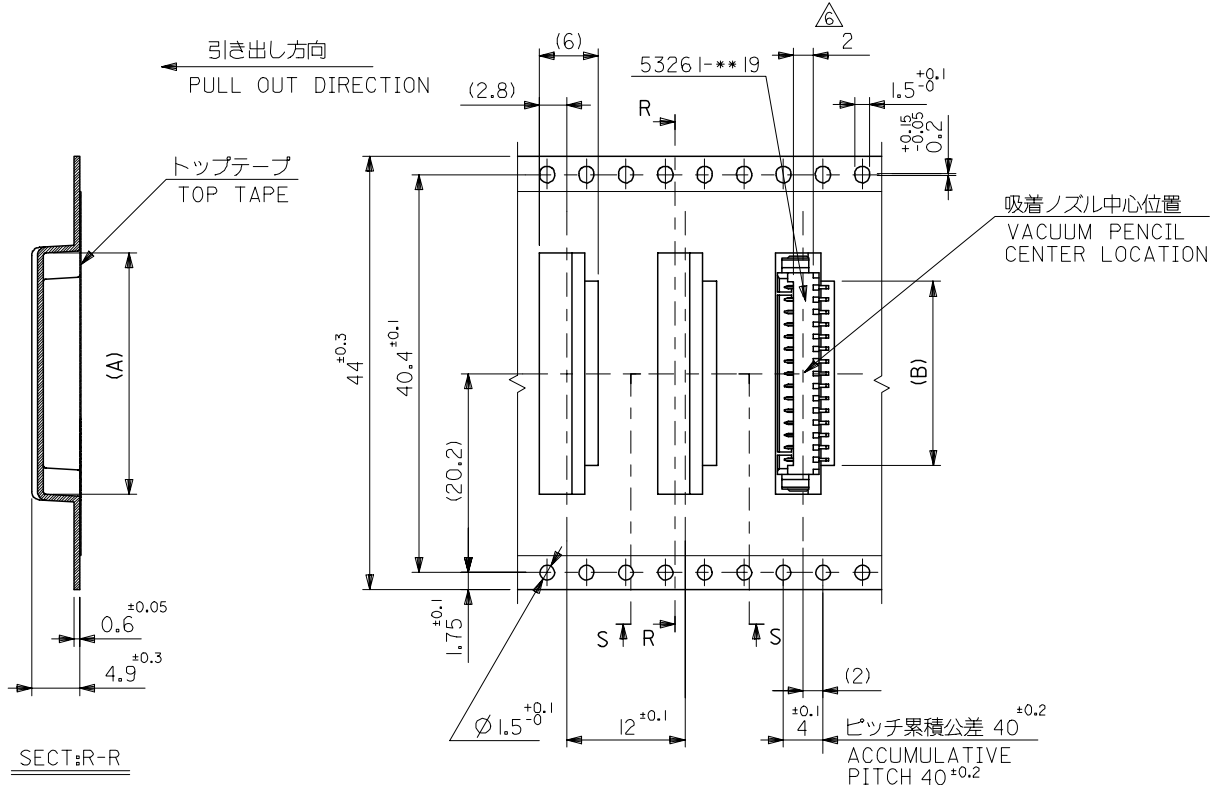
E

D

C

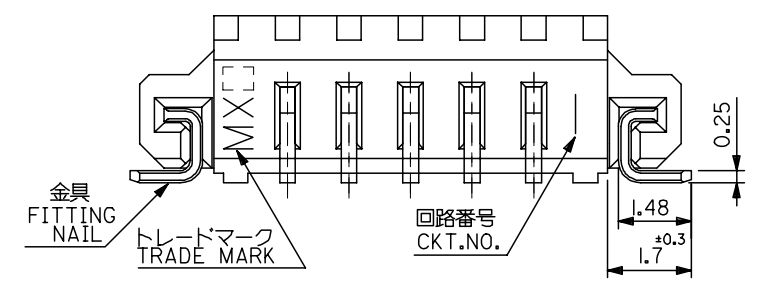
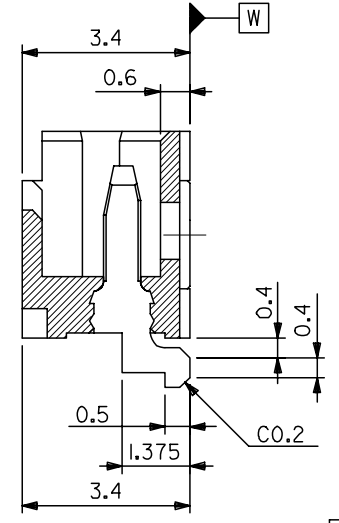
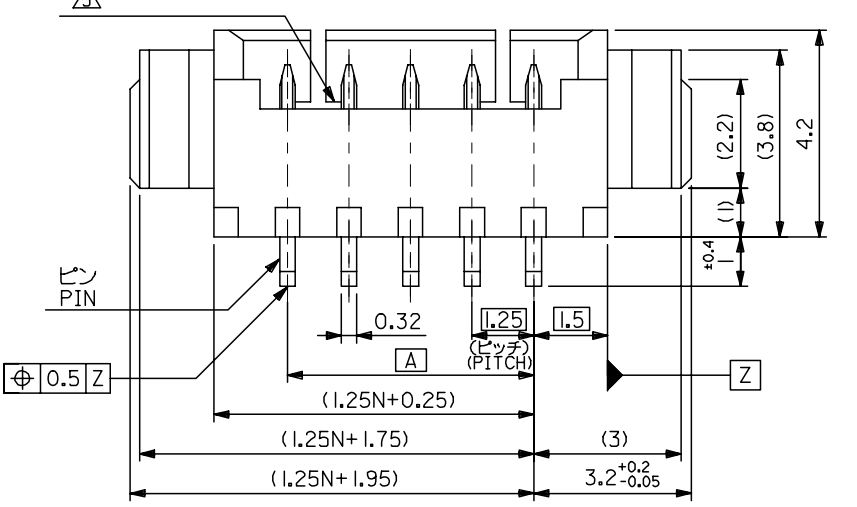
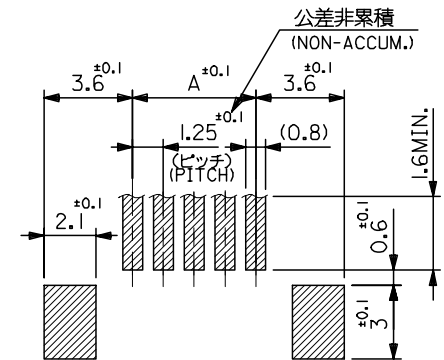
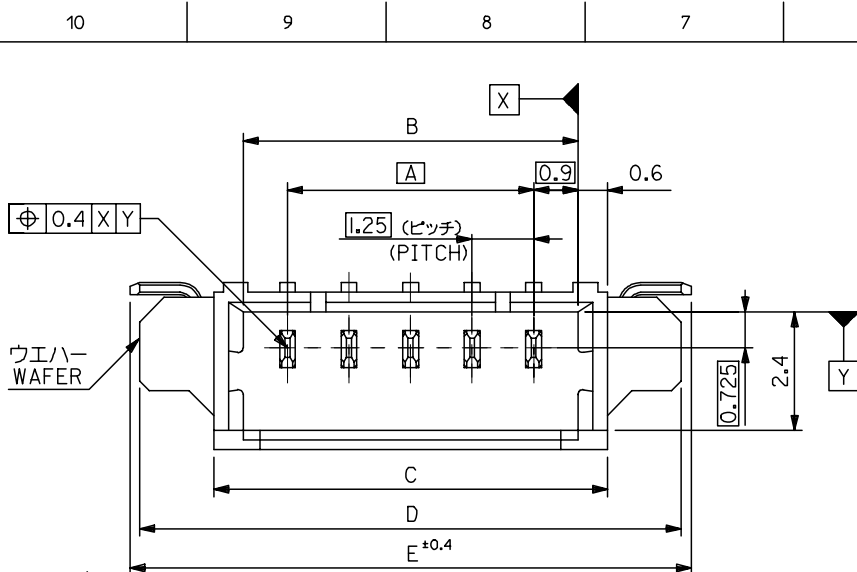
B

A



44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

REVISED	EC NO: J2008-0056	DRWN:KSAIT001	2007/07/31	CHKD:THARUYAMA	2007/07/31	APPR:NUKITA	2007/08/10	DESCRIPTION	MODEL NO.	53261-***71	44	49.4	45.4	18.7	24.5	53261-1571	15									
								GENERAL TOLERANCES (UNLESS SPECIFIED)	CARRIER TAPE WIDTH	D	C	B	A	MATERIAL. NO.	極致	17.45	23.25	53261-1471	14							
								10 UNDER ±0.2	DIMENSION STYLE	MM ONLY	SCALE	---	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION	TITLE										
								10 OVER 30 UNDER ±0.25	DRAWN BY	H. SHIMABUKUR	DATE	'04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG													
								30 OVER ±0.3	CHECKED BY	K. TOJO	DATE	'04/02/06	MOLEX INCORPORATED													
								ANGULAR ±3 °	APPROVED BY	M. SASAO	DATE	'04/02/06	MATERIAL. NO. 53261-1571													
								DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE CHART	DOCUMENT NO.	SD-53261-023	SHEET NO.													
									SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															



- 注記 NOTES**
1. 嵌合相手: 51021 シリウス  
MATES WITH: 51021 SERIES
  2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
PIN: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM  
金具  
FITTING NAIL: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
  - △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。  
LOCKING WINDOW:  
ONE PLACE FOR 2 AND 3 CKT. AND  
TWO PLACES FOR MORE THAN 3 CKT.
  4. ソルダータール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
  5. 本製品は 53261-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

REVISED EC NO: J2005-3130 DRW:NAIDA 2005/04/19 CHK:KTOYODA 2005/04/21 APPR:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE DRAWING		SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							